
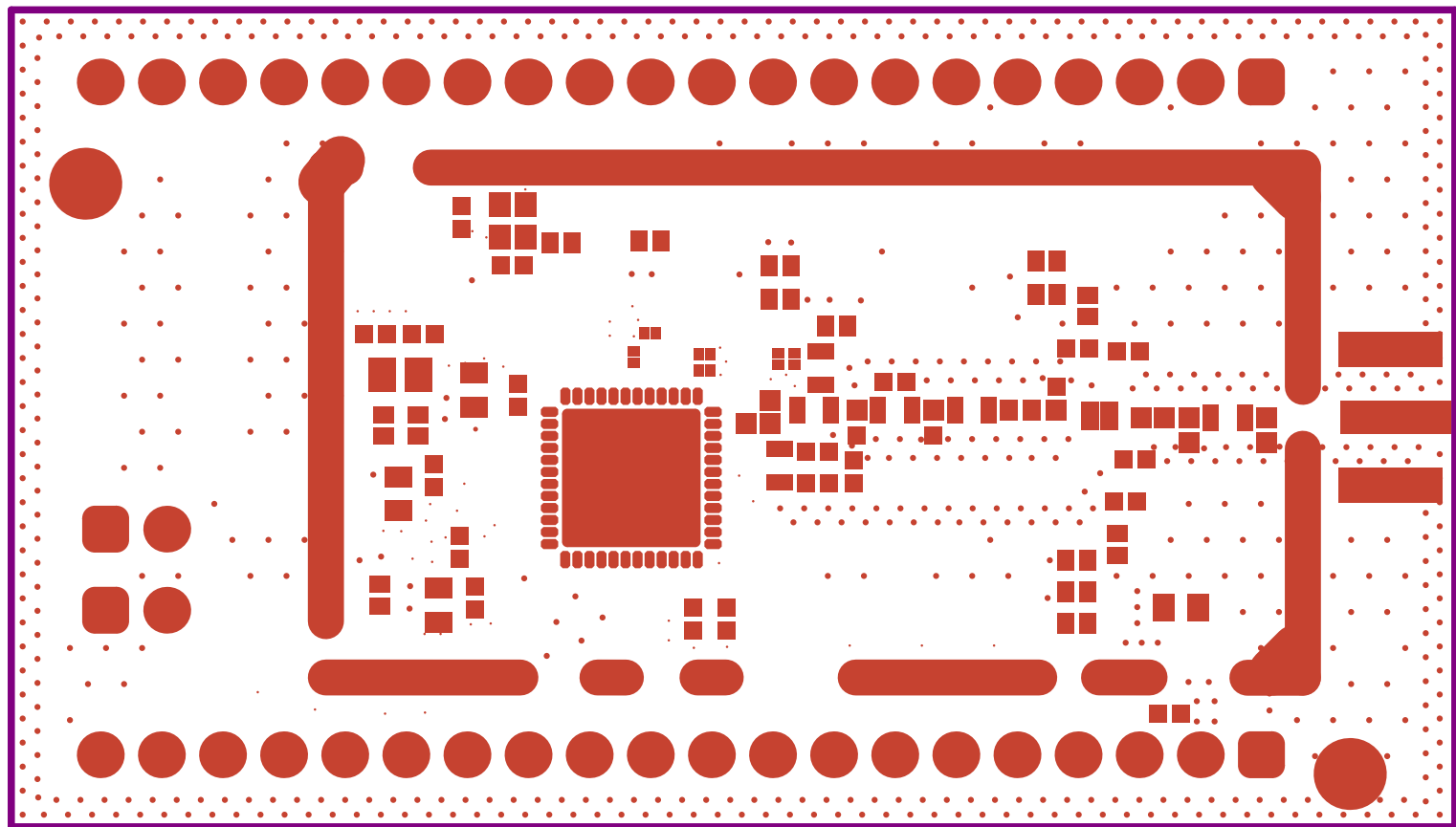

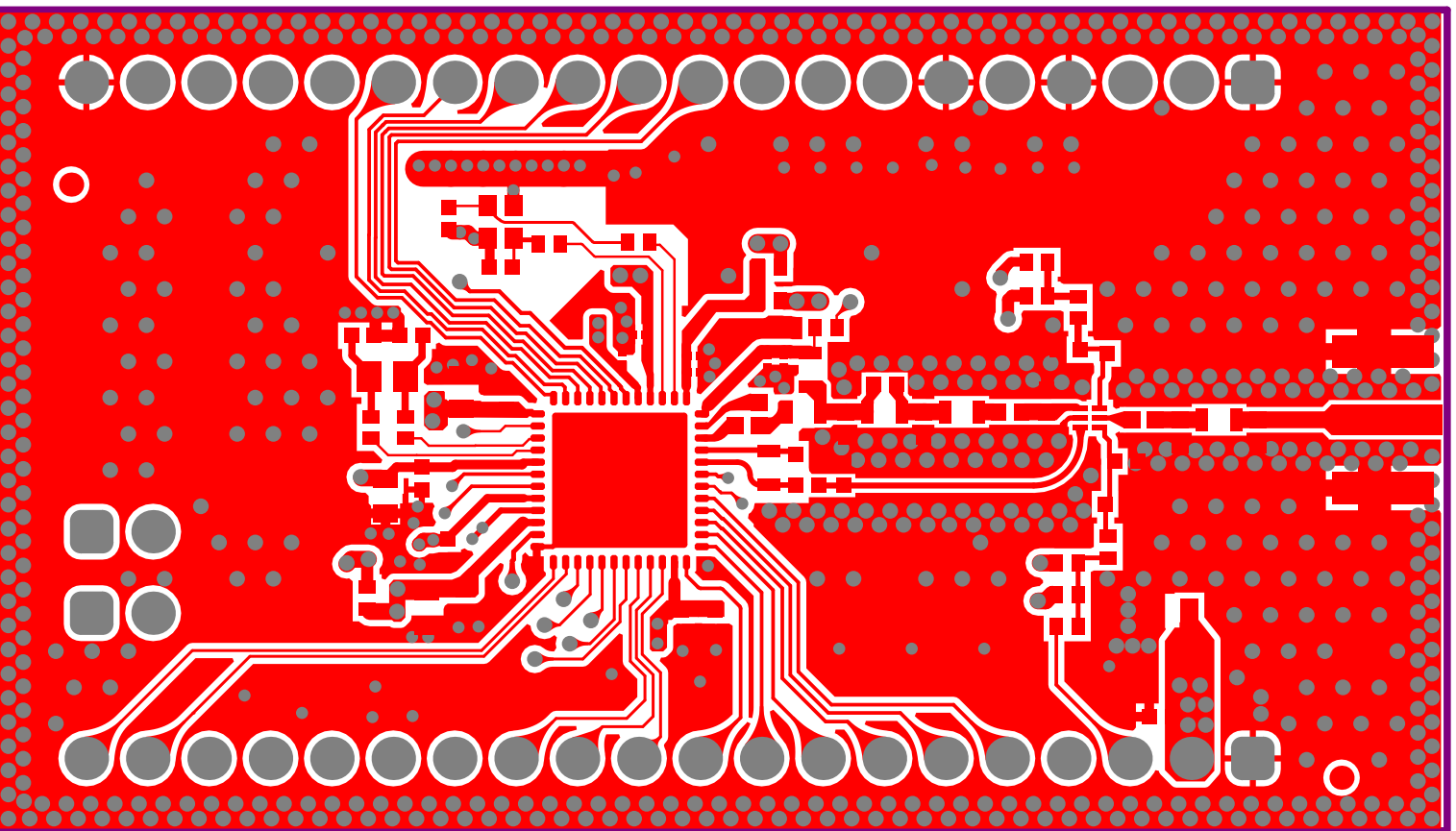



Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	

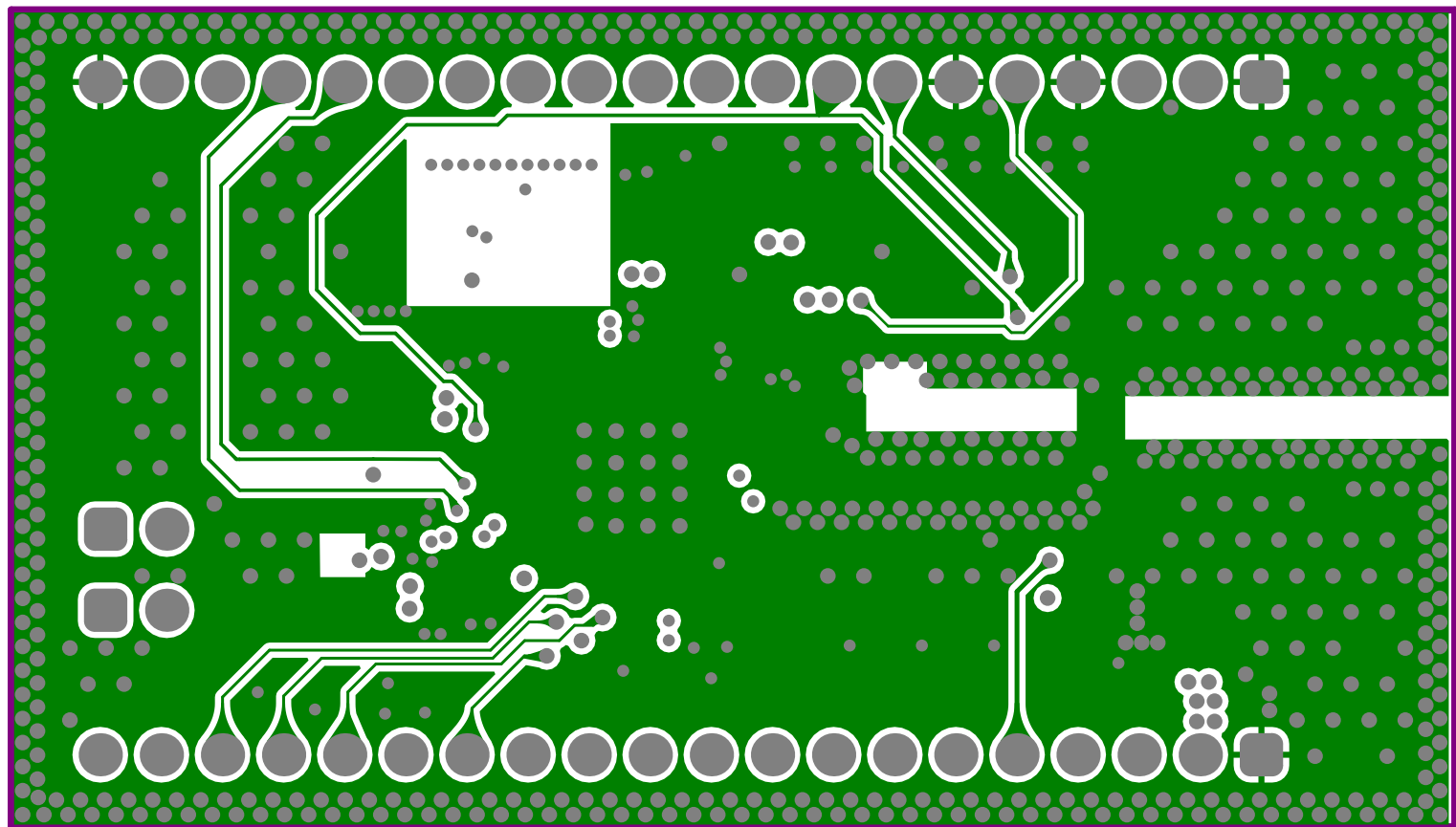



Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	

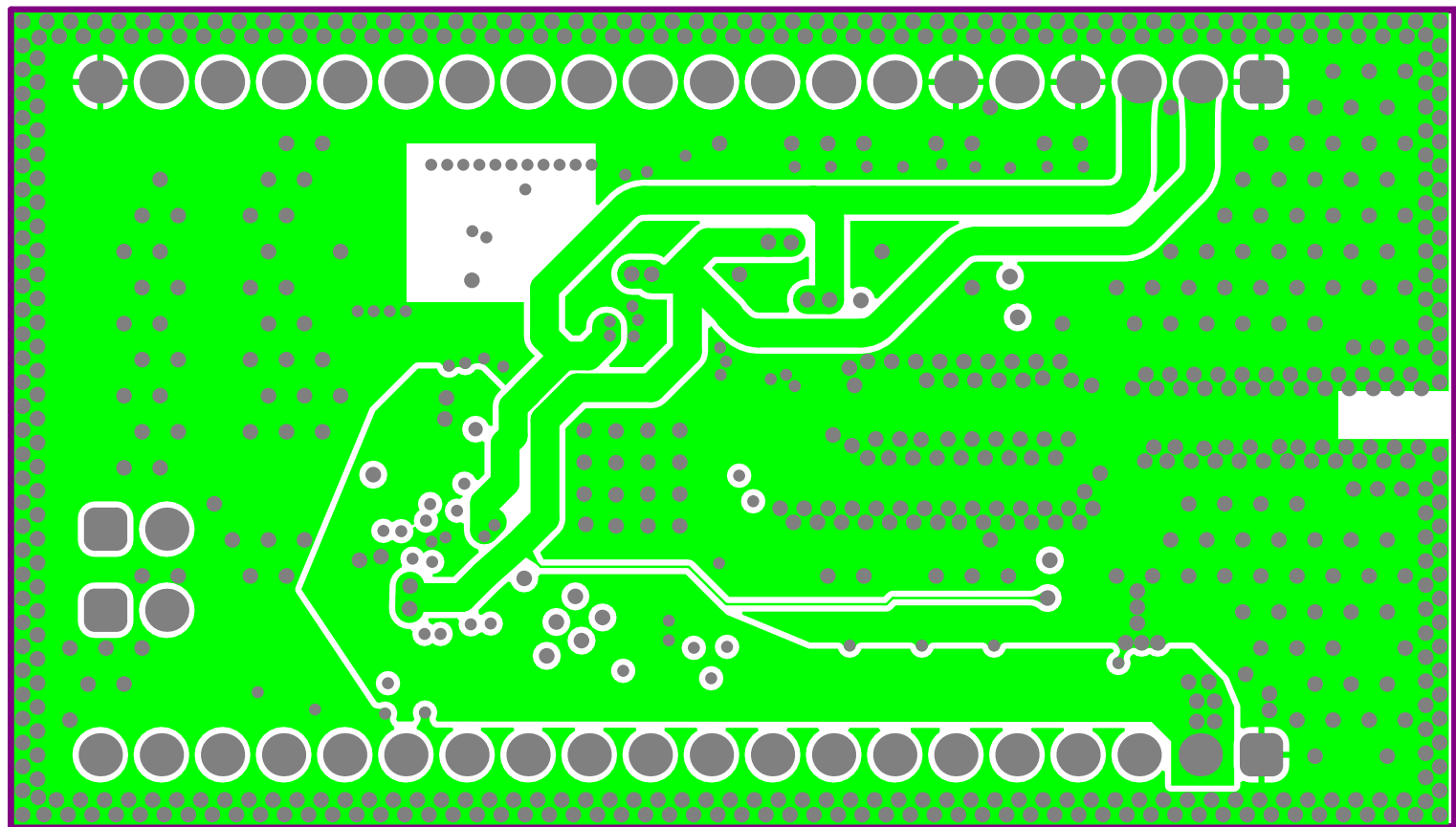
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.79mil	3.7	
1	Top Layer		1.38mil		
	Dielectric 1	1x106 + 1x2116	6.30mil	3.7	
2	Mid-Layer 1		1.38mil		
	Dielectric2	FR-4	24.02mil	5	
3	Mid-Layer 2		1.38mil		
	Dielectric3	1x106 + 1x2116	6.30mil	3.7	
4	Bottom Layer		1.38mil		
	Bottom Solder	Solder Resist	0.79mil	3.7	
	Bottom Overlay				




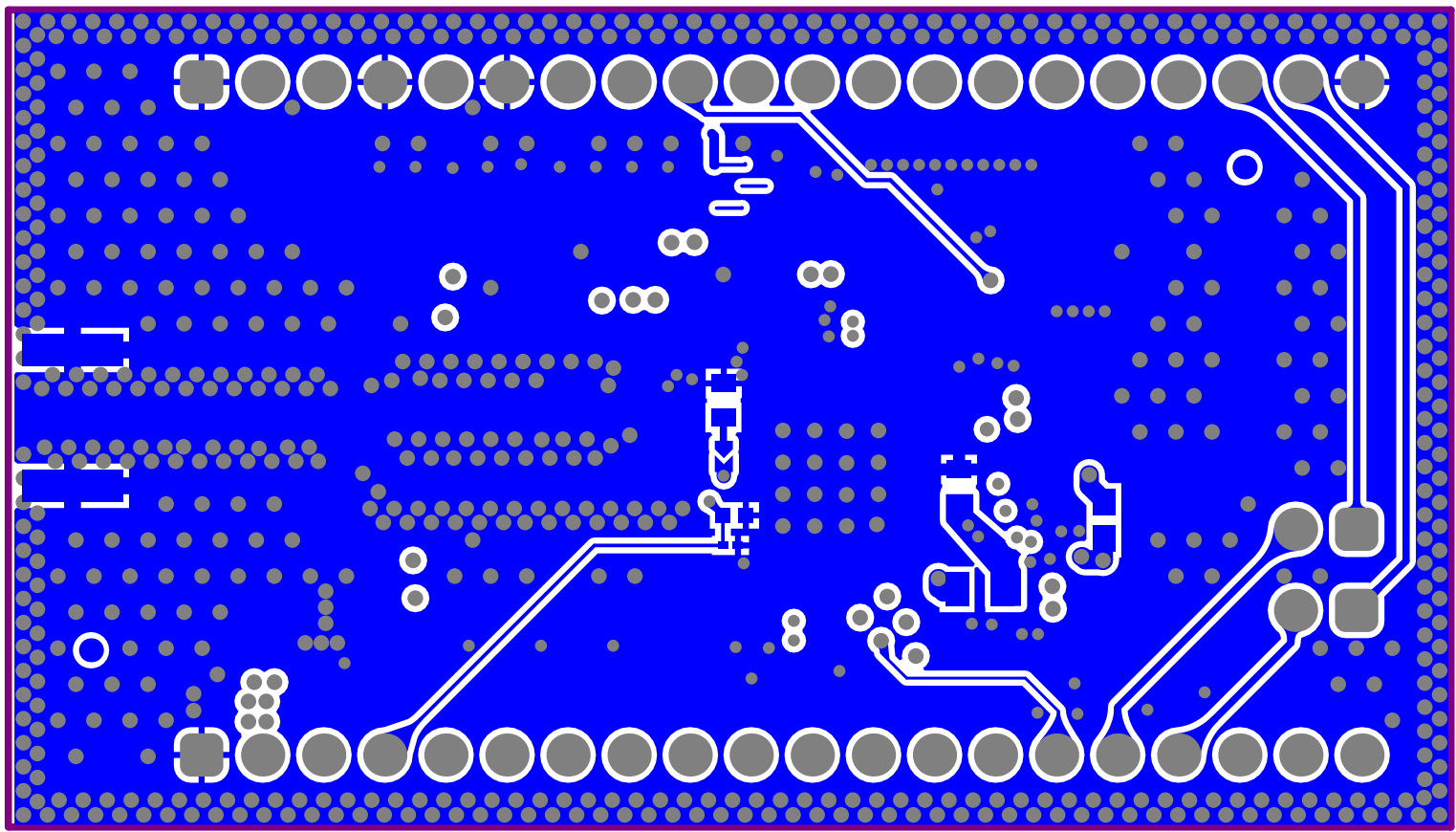
Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	




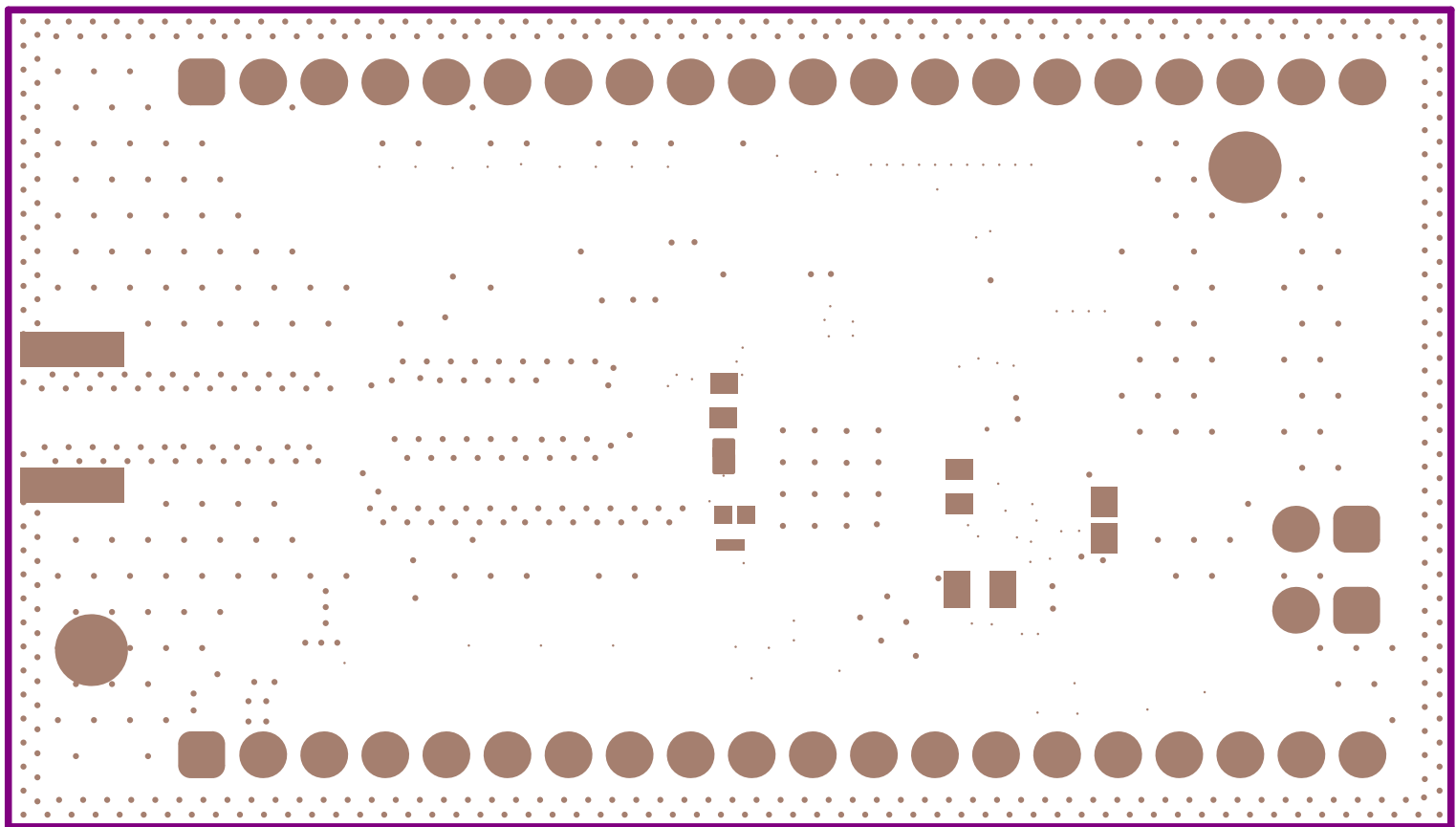
Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Mid-Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	




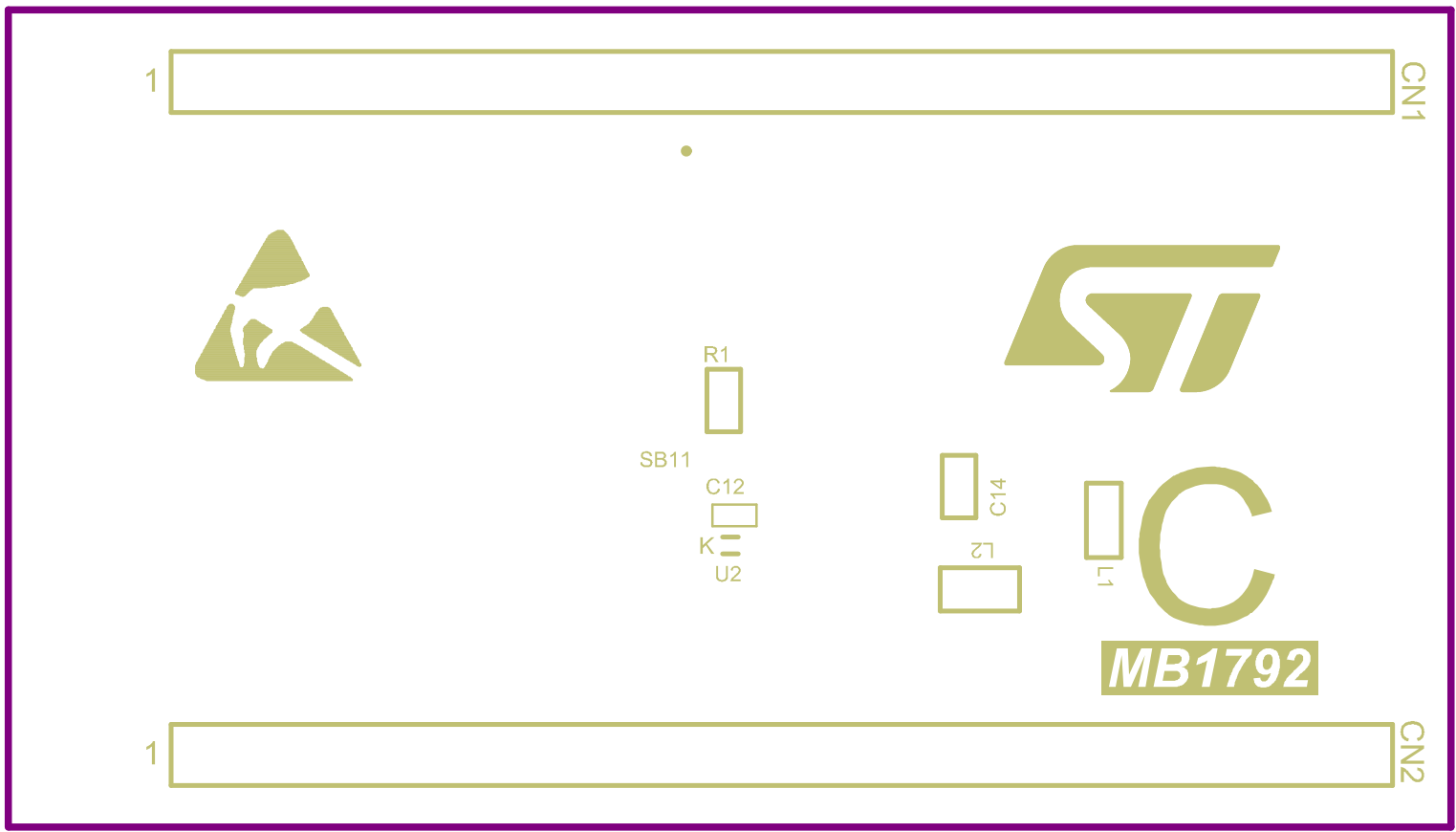
Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Mid-Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	




Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	



Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	



Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
○	44	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
☆	770	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
	814 Total												

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	27.56	7.1	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

☒TG-170

☐TG-150

☐TG-140

N/A

☒GREEN

☐BLUE

☐RED

☐BLACK

☒WHITE

☐YELLOW

☐BLACK

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

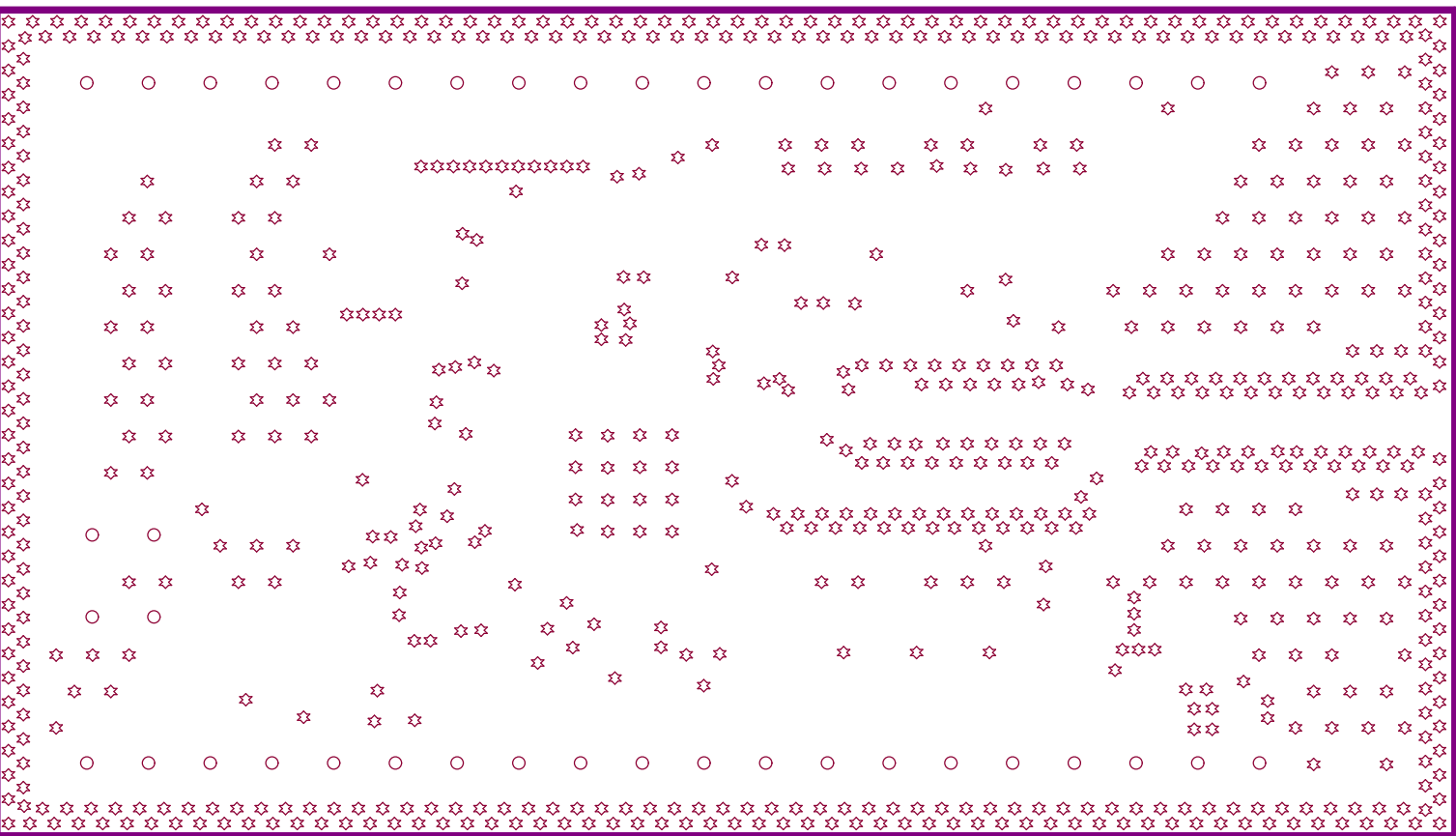
☐NO


☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒SOLDERMASK ☐NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_4Layers_WMBUS169MHz_RefBoard		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1792	
Date: 01-04-2022	Rev: A	